

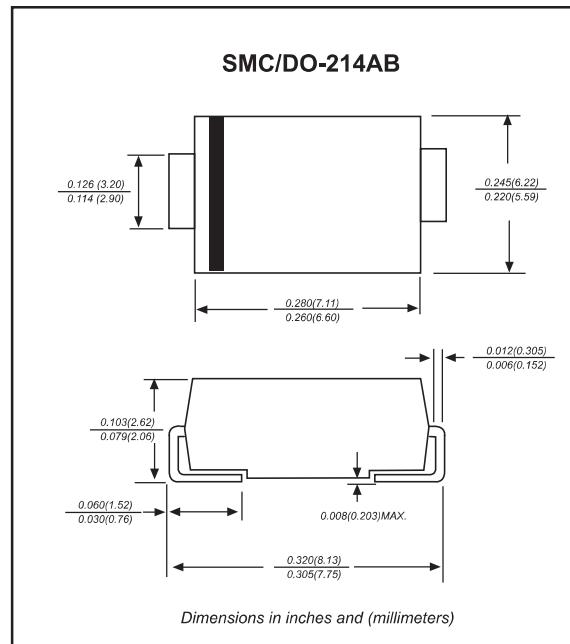
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ◆ Compliant to RoHS 2.0

Mechanical data

- ◆ **Case:** JEDEC DO-214AB molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}		V
Working Peak Reverse Voltage	V_{RWM}	200	
DC Blocking Voltage	V_R		
Average Rectified Forward Current (Rated V_R , $T_L = 70^\circ\text{C}$)	$I_{F(AV)}$	4	A
Nonrepetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	100	A
Operating Junction Temperature	T_J	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

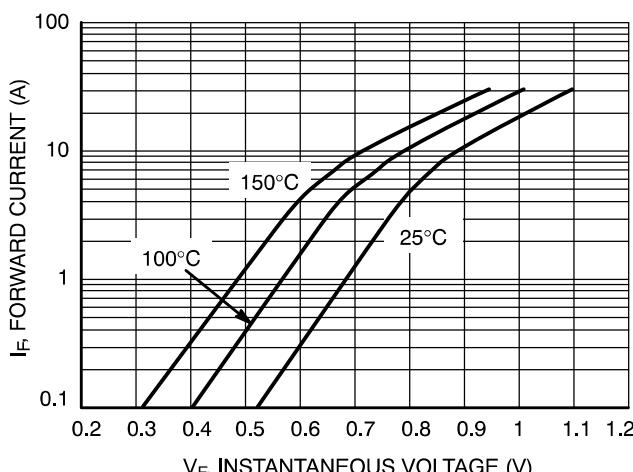
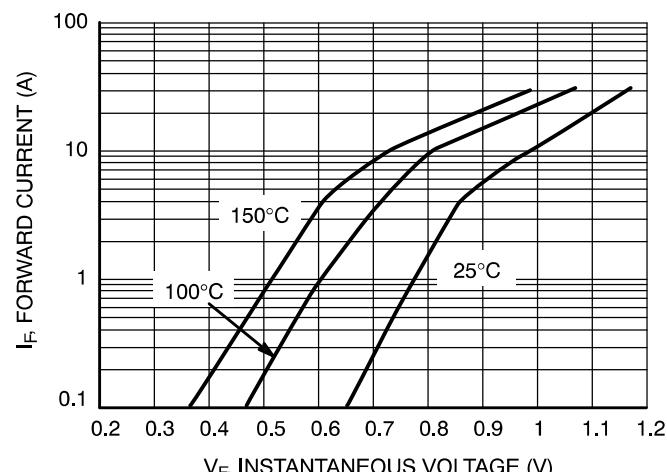
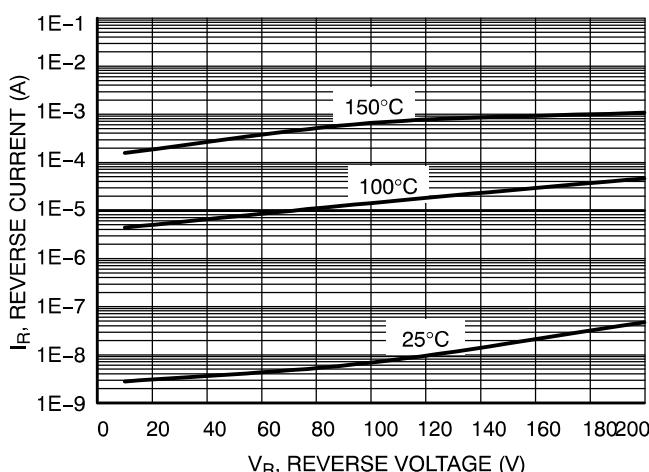
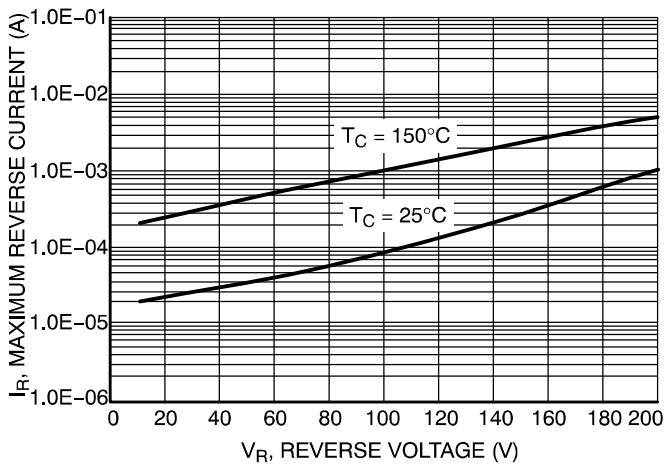
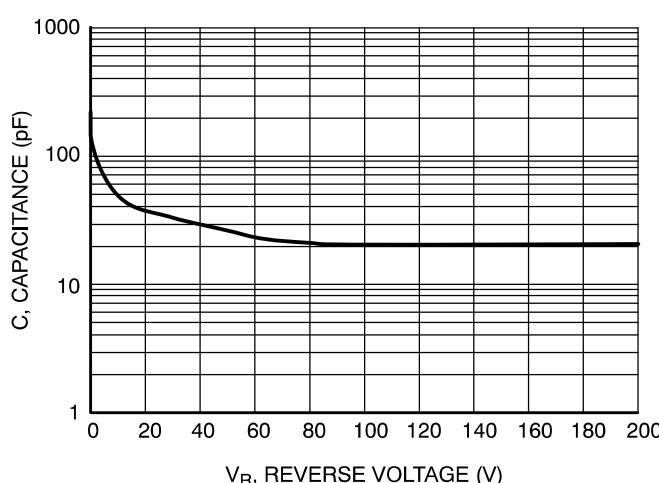
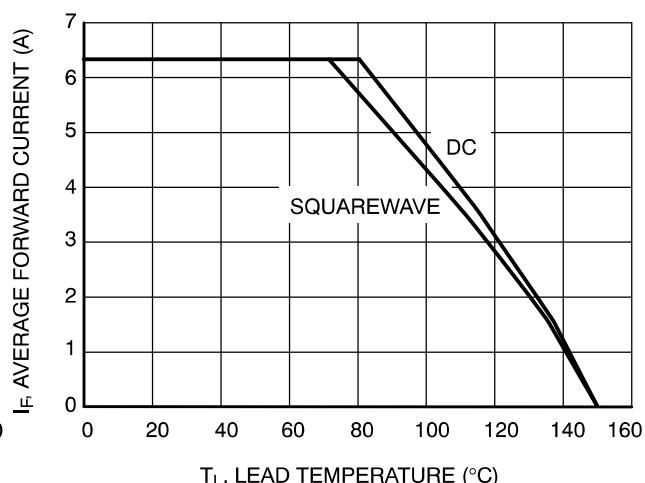
THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead	$R_{\theta JL}$	11	°C/W

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage ($I_F = 4 \text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 4 \text{ A}$, $T_J = 150^\circ\text{C}$)	V_F	0.86 0.61	V
Maximum Instantaneous Reverse Current (Rated V_R) (Rated DC Voltage, $T_J = 25^\circ\text{C}$) (Rated DC Voltage, $T_J = 150^\circ\text{C}$)	I_R	1.0 5.0	mA mA
Maximum Reverse Recovery Time ($I_F = 1.0 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$, $V_R = 30 \text{ V}$)	t_{rr}	35	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Rating and characteristic curves

Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

Figure 5. Typical Capacitance

Figure 6. Derating Curve

Rating and characteristic curves

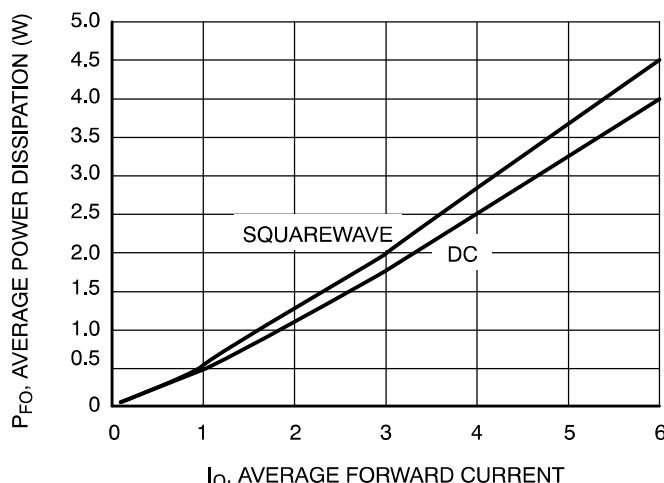
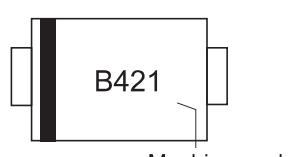


Figure 7. Power Dissipation

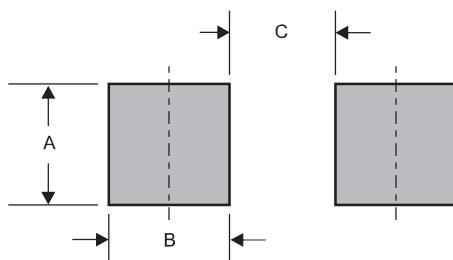
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode	1  2	1 

Marking

Type number	Marking code	Example
MBRS4201T3G-FS	B421	

Suggested solder pad layout

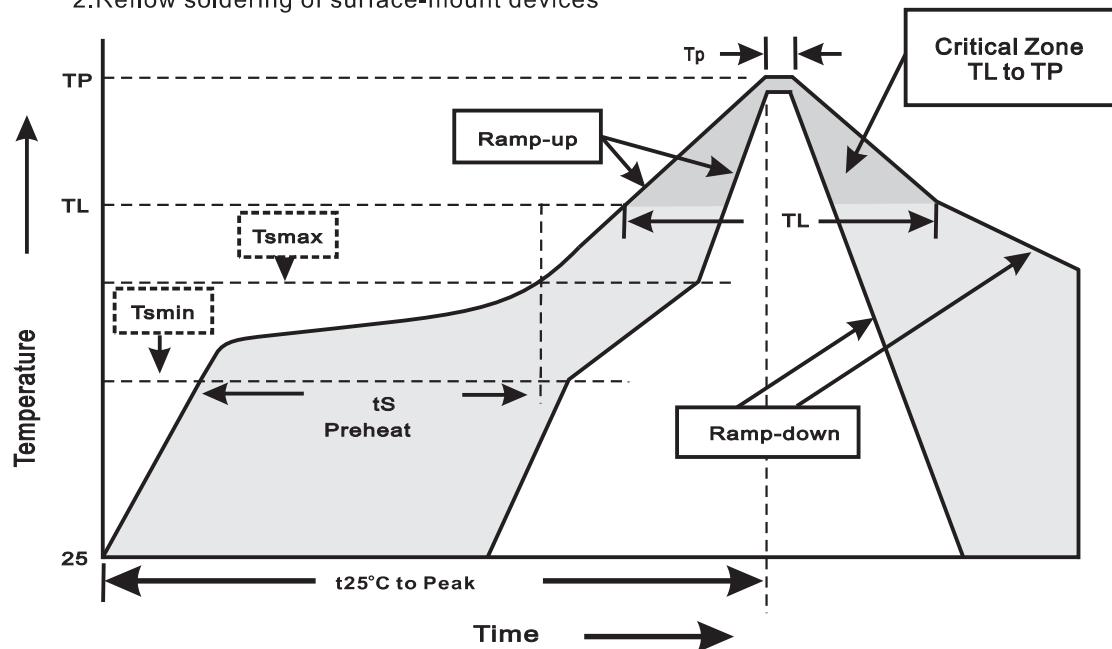


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC	0.132 (3.30)	0.100 (2.50)	0.176(4.40)

Suggested thermal profiles for soldering processes

1. Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2. Reflow soldering of surface-mount devices



3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes